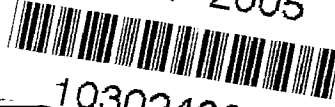


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7217/69220 S-16-05

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To the Honorable Commissioner of Patents and Trademarks

documents or copy thereof.

1. Name of conveying party(ies):

Noritaka Sato  
Tsutomu Noguchi  
Hiroyuki Mori

Name: Sony Corporation  
Internal Address:

Additional name(s) of conveying party(ies) attached?  Yes  
 No

Name of receiving party(ies):

3. Nature of Conveyance:

Assignment  Merger  
 Security Agreement  Change of Name  
 Other

Street Address: 7-35 Kitashinagawa 6-chome,  
Shinagawa-ku, Tokyo, 141-0032 JAPAN

City \_\_\_\_\_ State \_\_\_\_\_ ZIP \_\_\_\_\_

Execution Date: December 21, 2004, December 21, 2004, December 21, 2004

Additional name(s) & address(es) attached?  Yes  No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is

A. Patent Application No.(s)

10/512 491

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Jay H. Maioli  
Internal Address: Cooper & Dunham LLP

Street Address: 1185 Avenue of the Americas

City: New York State: New York ZIP: 10036

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): ..... \$ 40.00

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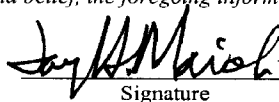
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9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Jay H. Maioli, Reg. No. 27,213  
Name of Person Signing

  
Signature

May 11, 2005  
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**ASSIGNMENT**

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in RESIN COMPOSITION for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 6-7-35 Kitashinagawa, Shinagawa-Ku, Tokyo, Japan (hereinafter reference as ASSIGNEE) are desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereof;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereof;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number \_\_\_\_\_, Filing Date \_\_\_\_\_

This assignment executed on the dates indicated below.

Noritaka Sato

Name of first or sole inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of first or sole inventor

Noritaka Sato

Dec 21, 2004

Signature of first or sole inventor

Date of this assignment

Tsutomu Noguchi

Name of second inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of second inventor

Tsutomu Noguchi

Dec. 21, 2004

Signature of second inventor

Date of this assignment

Hirovuki Mori

Name of third inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of third inventor

Hirovuki Mori

Dec. 21, 2004

Signature of third inventor

Date of this assignment